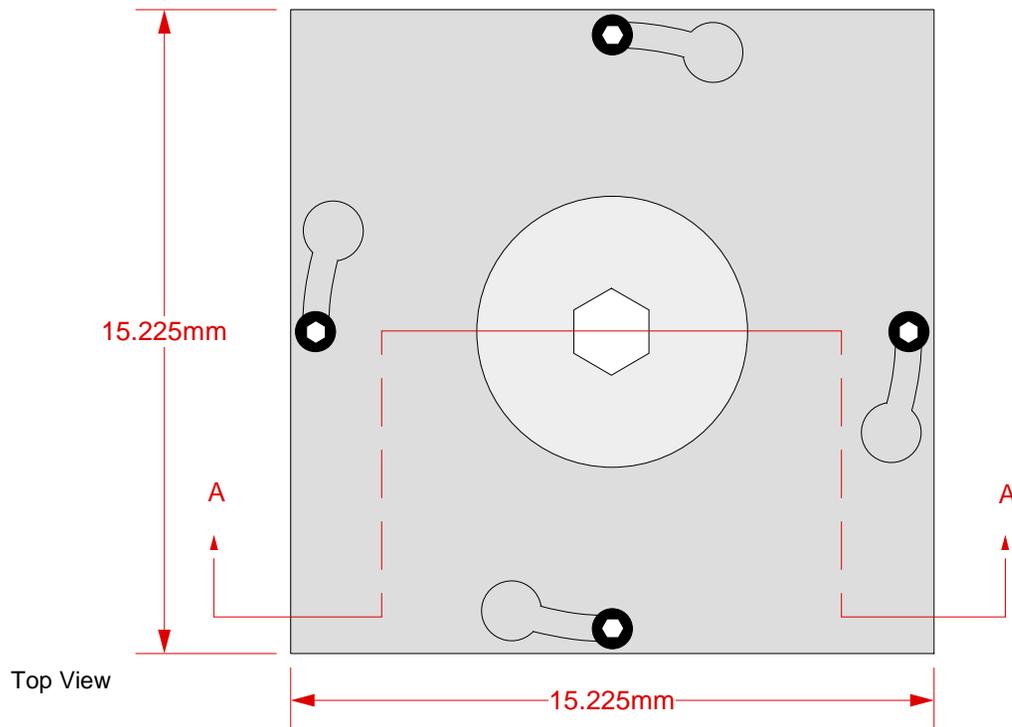


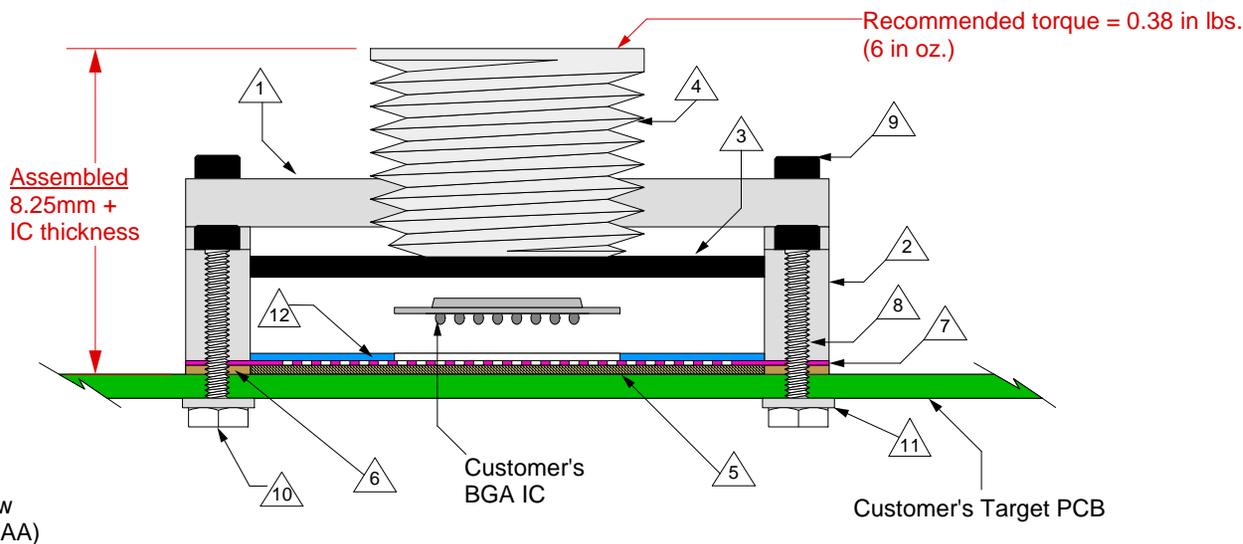
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Top View



Side View
(Section AA)

- △ 1 Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm.

- △ 2 Socket base: Black anodized Aluminum.
Thickness = 6.5mm.

- △ 3 Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm.

- △ 4 Compression screw: Black anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm.

- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm.

- △ 6 Elastomer Guide: Non-clad FR4.
Thickness = 0.725mm.

- △ 7 Ball Guide: Kapton polyimide.

- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.

- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.

- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.

- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD
0.64mm thickness.

- △ 12 IC Guide: Torlon

SG-BGA-6142 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: D

Drawing: H. Hansen

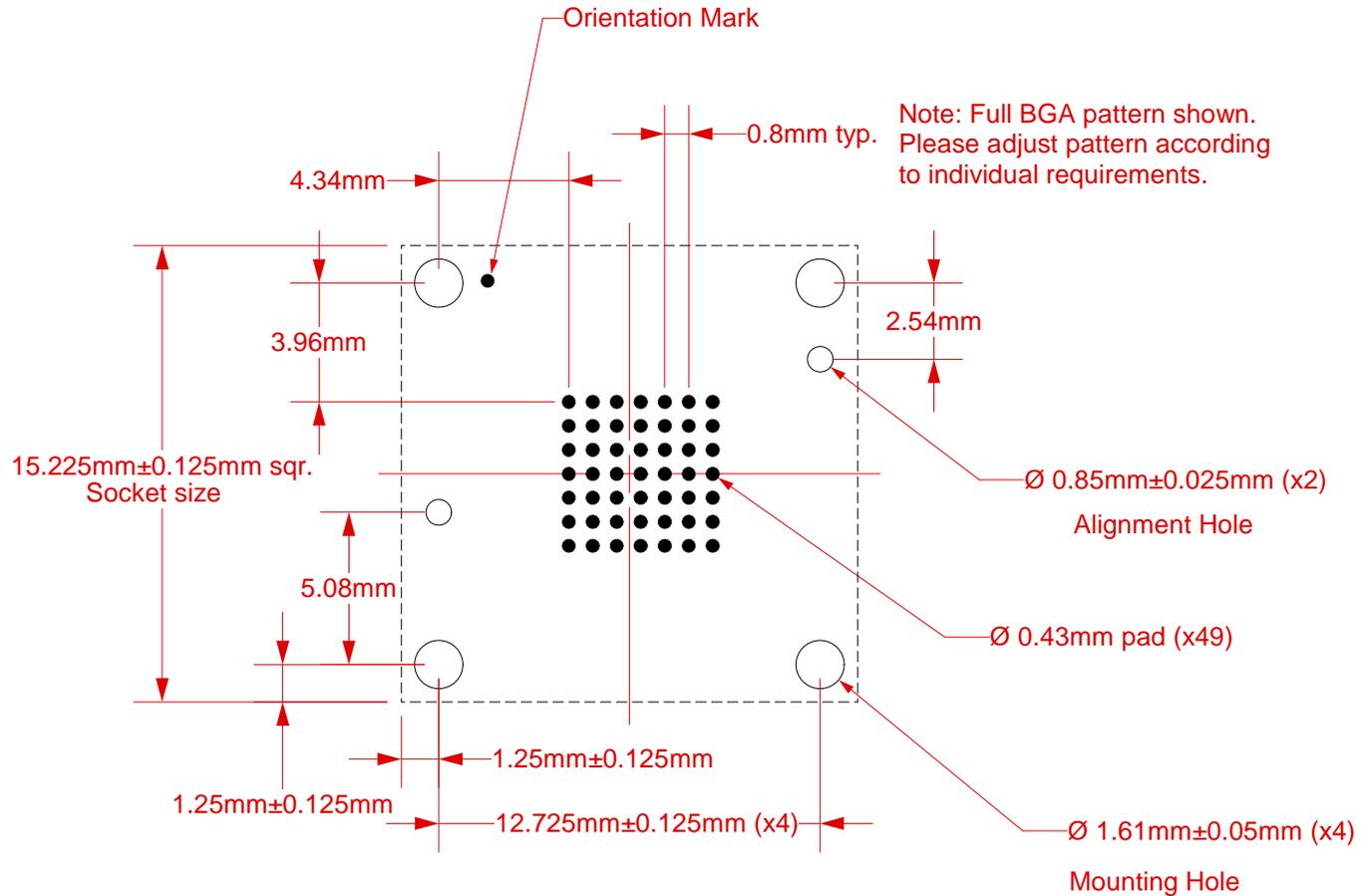
Date: 1/10/05

File: SG-BGA-6142 Dwg

Modified: 05/07/14, DH

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

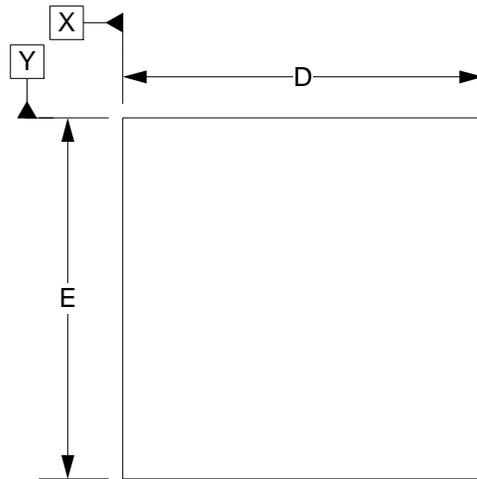


Target PCB Recommendations

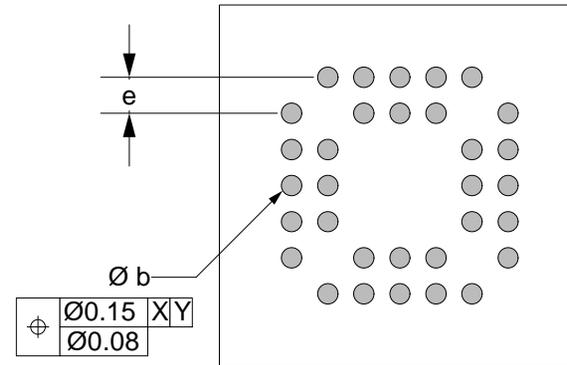
Total thickness: 2.4mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

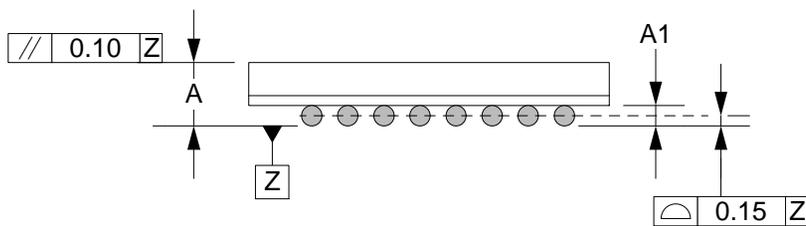
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SG-BGA-6142 Drawing</p>		Status: Released	Scale: 4:1	Rev: D
	<p>Drawing: H. Hansen</p>		<p>Date: 1/10/05</p>		
	<p>File: SG-BGA-6142 Dwg</p>		<p>Modified: 05/07/14, DH</p>		



Top View



Bottom View Array: 7 x 7



Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.



Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.



Datum Z (seating plane) is defined by the spherical crowns of the solder balls.



Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.65
A1	0.25	0.44
b	0.5	0.6
D	7.0 BSC	
E	7.0 BSC	
e	0.8 BSC	

	SG-BGA-6142 Drawing	Status: Released	Scale: -	Rev: D
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		File: SG-BGA-6142 Dwg	Modified: 05/07/14, DH	